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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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DESCRIPTION

The Microsemi LX5511 is a power amplifier that is optimized for WLAN applications in the 2.3GHz – 2.5GHz frequency range. The LX5511 Power Amplifier is implemented as a two-stage monolithic microwave integrated circuit (MMIC) with active bias and output pre-matching.

The device is manufactured with an InGaP/GaAs Heterojunction Bipolar Transistor (HBT) IC process (MOCVD). With a single low voltage supply of 3.3V 26dB power gain between 2.3-2.5GHz, at a low quiescent current of 90mA.

For 20dBm OFDM output power (64QAM, 54Mbps), the PA provides a low EVM (Error-Vector Magnitude) of less than 3.0%, and consumes 170mA total DC current..

The LX5511 is available in a 16-pin 3mmx3mm micro-lead quad package (MLPQ). The compact footprint, low profile, and thermal capability of the MLPQ package makes the LX5511 an ideal solution for medium-gain power amplifier requirements for IEEE 802.11b/g applications

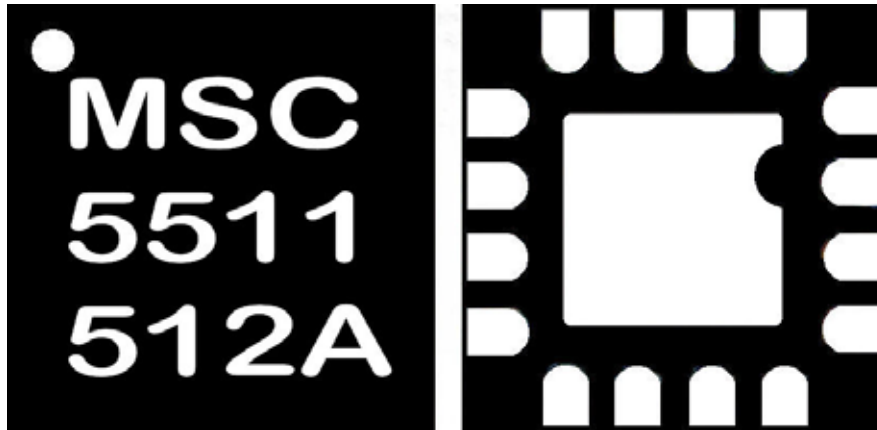
IMPORTANT: For the most current data, consult MICROSEMI's website: <http://www.microsemi.com>

KEY FEATURES

- Advanced InGaP HBT
- 2.3-2.5GHz Operation
- Single-Polarity 3.3V Supply
- Quiescent Current 90mA
- Power Gain 26 dB
- Total Current 150mA for Pout=18 dBm OFDM
- EVM<3 %, 2.4% Typical 54Mbps/64QAM
- Small Footprint: 3x3mm²
- Height 0.9mm

APPLICATIONS

- IEEE 802.11b/g

PRODUCT HIGHLIGHT

PACKAGE ORDER INFO

LQ	Plastic MLPQ
	16-Pin
RoHS Compliant / Pb-free	
LX5511LQ	

Note: Available in Tape & Reel. Append the letters "TR" to the part number. (i.e. LX5511LQ-TR)



Microsemi[®]

INFORMATION

Thank you for your interest in Microsemi[®] IPG products.

The full data sheet for this device contains proprietary information.

To obtain a copy, please contact your local Microsemi sales representative. The name of your local representative can be obtained at the following link

<http://www.microsemi.com/contact/contactfind.asp>

or

Contact us directly by sending an email to:

IPGdatasheets@microsemi.com

Be sure to specify the data sheet you are requesting and include your company name and contact information and or vcard.

We look forward to hearing from you.